

ABSTRACT

5 An improved PCB bond pad (22, 40, 50, 60) having a dimensioned
geometry that improves solder re-flow and facilitates outgassing of bubbles
generated in solder during re-flow to reduce voiding. The improved PCB bond
pad design is particularly useful to improve re-flow for RF devices that are
sensitive to voiding in solder after re-flow and provides an excellent ground
plane/heat sink connection. The present invention includes a printed circuit board
10 (PCB) having a patterned bond pad defining solder channels (30, 42, 52, and 62).
During re-flow, bubbles outgas through the channels from under a contact pad
(34) of an overlying IC device thereby providing nearly 100 percent solder
coverage at interface of device exposed pad and PCB bond pad.